

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

[75] Inventor: Yoshihiko Asanuma, Tochigi, Japan

[73] Assignee: Showa Aluminum Kabushiki Kaisha, Osaka, Japan

[**] Term: 14 Years

[21] Appl. No.: 154,971

[22] Filed: May 30, 1980

[30] Foreign Application Priority Data

Mar. 31, 1980 [TW] Taiwan 6930607

[51] Int. Cl. D13-03

[52] U.S. Cl. D13/23

[58] Field of Search D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

[56] References Cited

U.S. PATENT DOCUMENTS

2,949,283	8/1960	Smith	174/16 HS X
3,163,207	12/1964	Schultz	174/16 HS X
3,180,404	4/1965	Nelson et al.	351/81 X
3,187,812	6/1965	Staver	174/16 HS X

Primary Examiner—Susan J. Lucas
Attorney, Agent, or Firm—Armstrong, Nikaido, Marmelstein & Kubovcik

[57] CLAIM

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

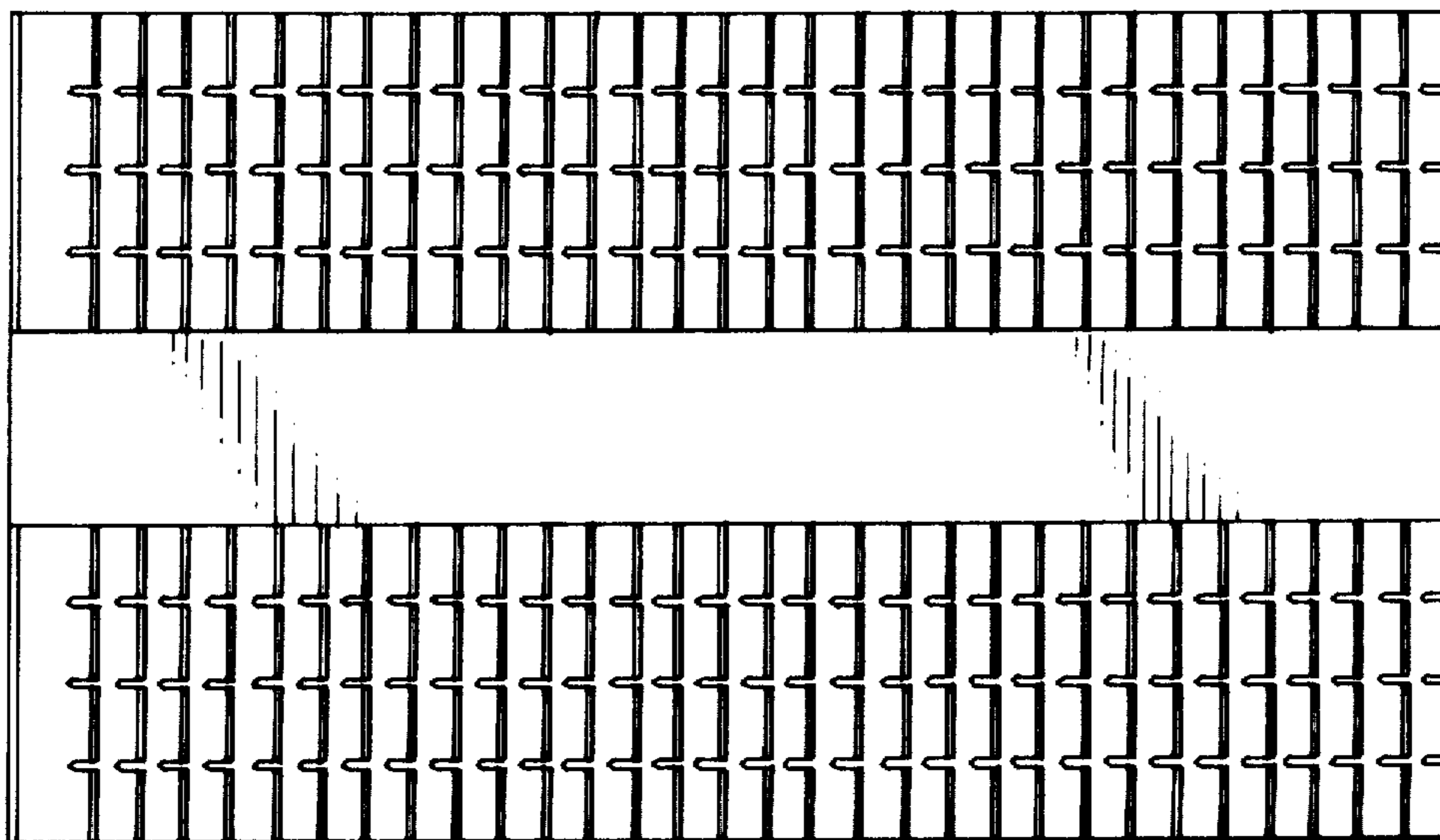
DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semiconductor components showing the new design;

FIG. 2 is a plan view thereof;

FIG. 3 is a right side view thereof; and

FIG. 4 is a sectional view taken on line 4-4 of FIG. 1.



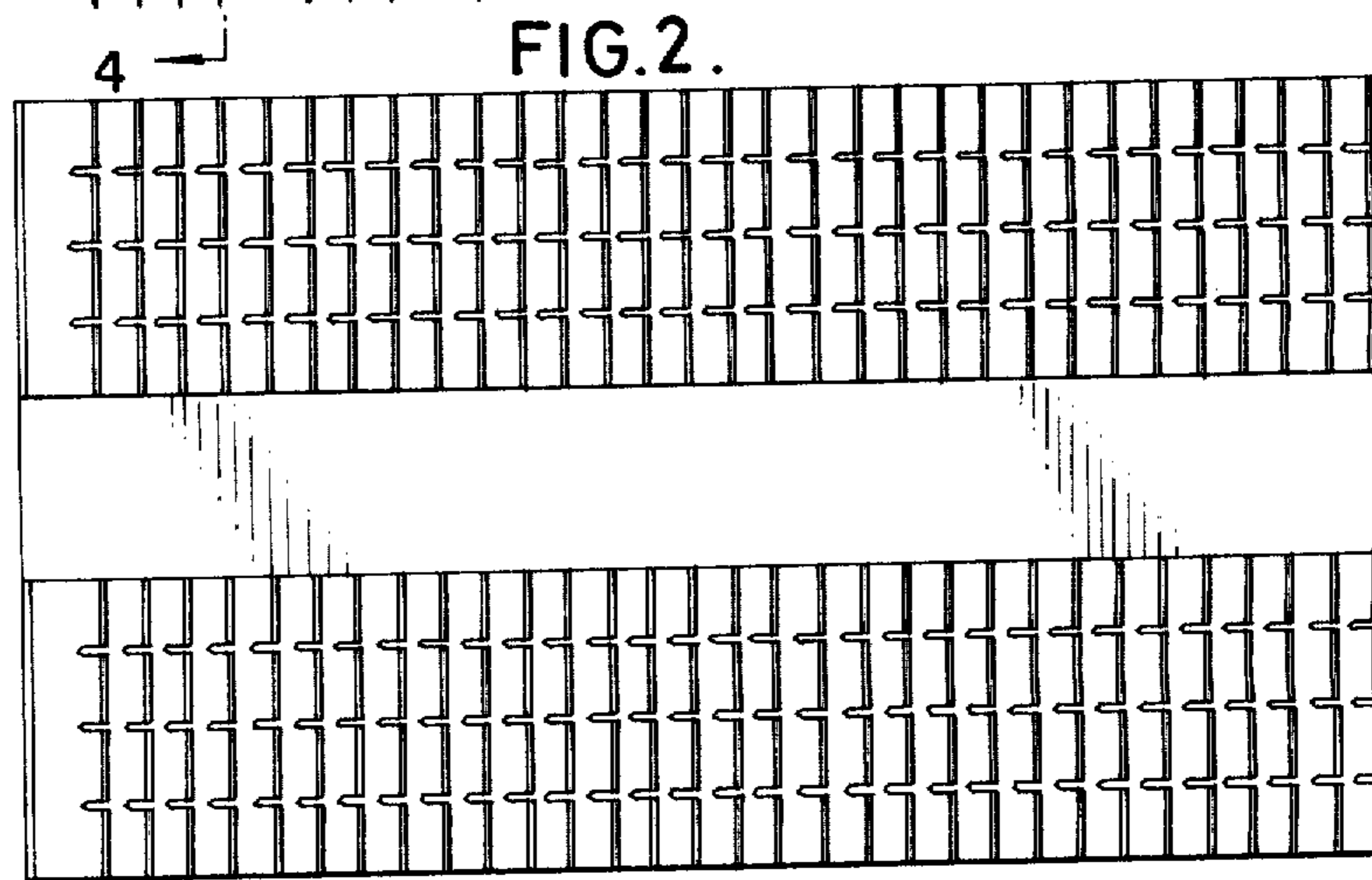
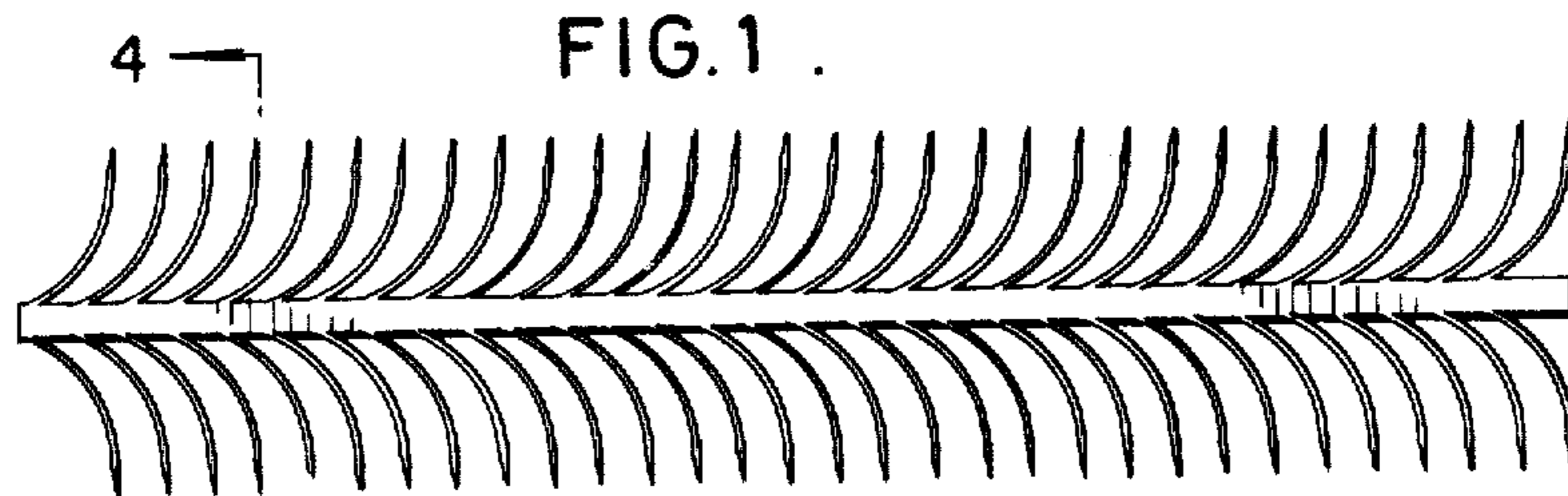


FIG. 3 .

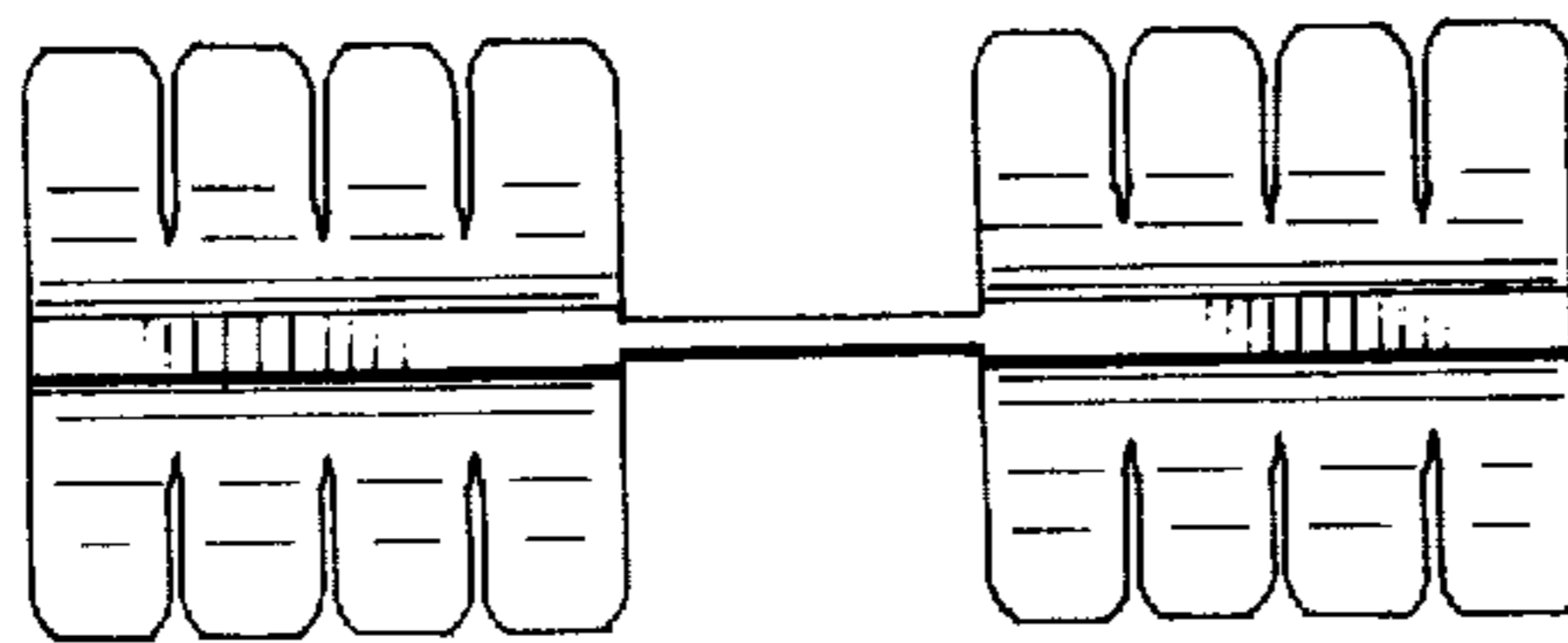


FIG. 4 .

